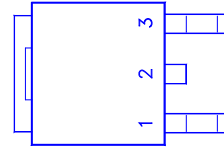
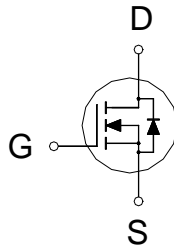




PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
600V	4.85Ω	2A



- 1. GATE
- 2. DRAIN
- 3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ °C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	600	V
Gate-Source Voltage		V_{GS}	±30	V
Continuous Drain Current ²	$T_C = 25\text{ °C}$	I_D	2	A
	$T_C = 100\text{ °C}$		1.3	
Pulsed Drain Current ^{1, 2}		I_{DM}	8	
Avalanche Current ³		I_{AS}	2	
Avalanche Energy ³		E_{AS}	20	mJ
Power Dissipation	$T_C = 25\text{ °C}$	P_D	46	W
	$T_C = 100\text{ °C}$		18	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2.7	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

²Limited only by maximum temperature allowed

³ $V_{DD} = 50V$, $L = 10mH$,starting $T_J = 25\text{ °C}$

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ °C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	600			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3.1	4	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 30V$			±100	nA
Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 600V, V_{GS} = 0V, T_C = 25\text{ °C}$			1	μA
		$V_{DS} = 480V, V_{GS} = 0V, T_C = 100\text{ °C}$			10	

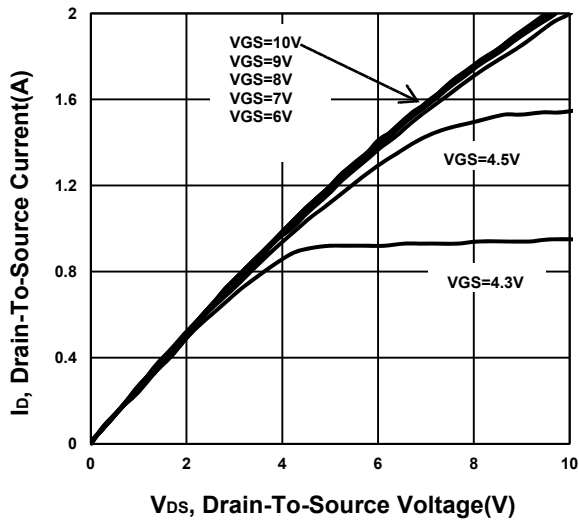
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 1A$		3.9	4.85	Ω
Forward Transconductance ¹	g_{fs}	$V_{DS} = 15V, I_D = 1A$		2		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		281		pF
Output Capacitance	C_{oss}			37		
Reverse Transfer Capacitance	C_{rss}			7		
Total Gate Charge ²	Q_g	$V_{DD} = 480V, I_D = 2A, V_{GS} = 10V$		8		nC
Gate-Source Charge ²	Q_{gs}			1.2		
Gate-Drain Charge ²	Q_{gd}			3.3		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{GS} = 10V, V_{DD} = 300V,$ $I_D = 2A, R_G = 25\Omega$		28		nS
Rise Time ²	t_r			60		
Turn-Off Delay Time ²	$t_{d(off)}$			58		
Fall Time ²	t_f			66		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$)						
Continuous Current ³	I_S				2	A
Forward Voltage ¹	V_{SD}	$I_F = 2A, V_{GS} = 0V$			1	V
Reverse Recovery Time	t_{rr}	$I_F = 2A, di_F/dt = 100A / \mu S$		279		nS
Reverse Recovery Charge	Q_{rr}			1.1		uC

¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

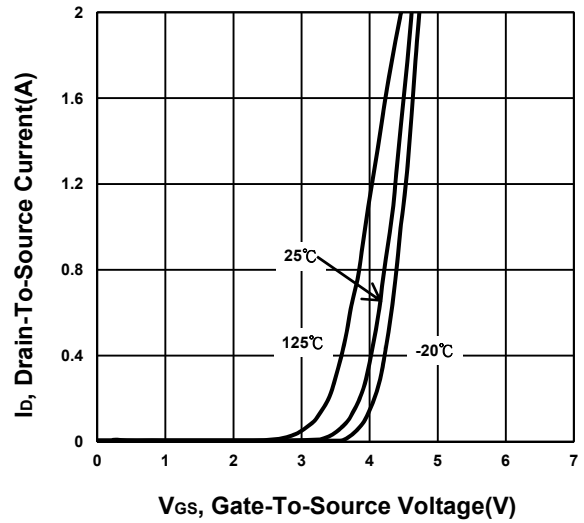
²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

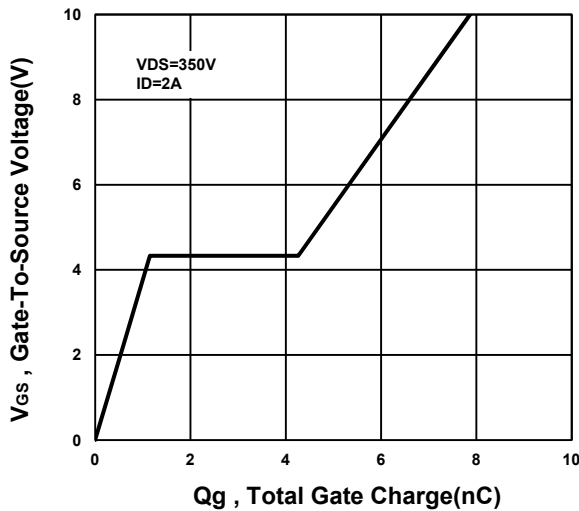
Output Characteristics



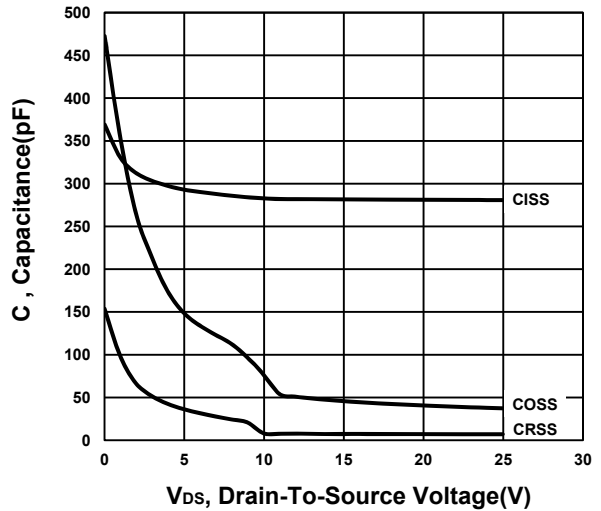
Transfer Characteristics



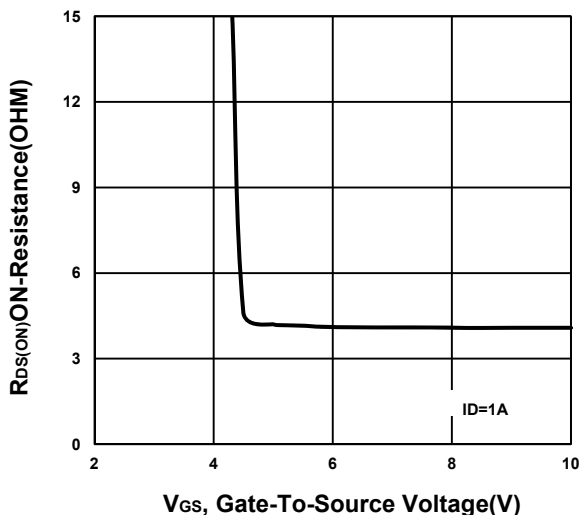
Gate charge Characteristics



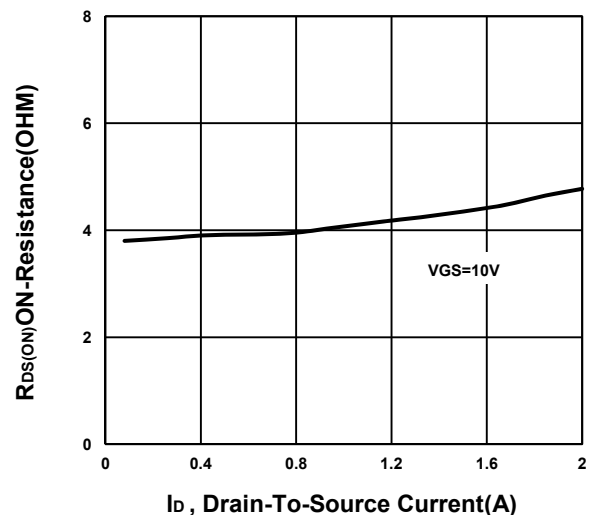
Capacitance Characteristic



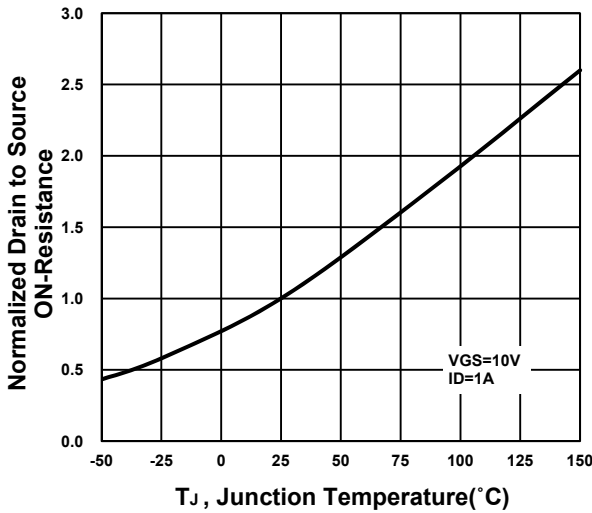
On-Resistance VS Gate-To-Source



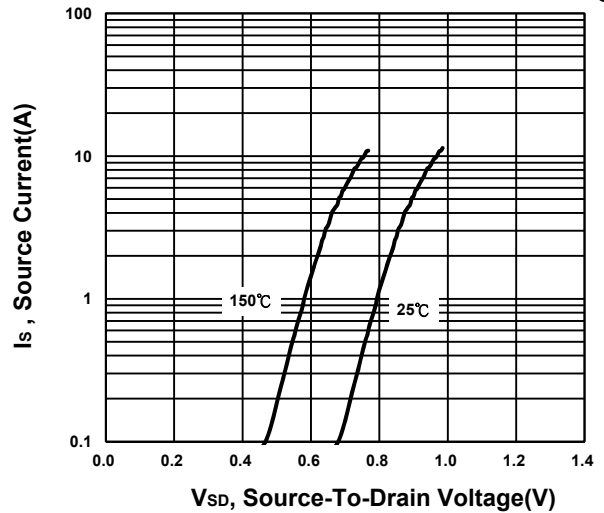
On-Resistance VS Drain Current



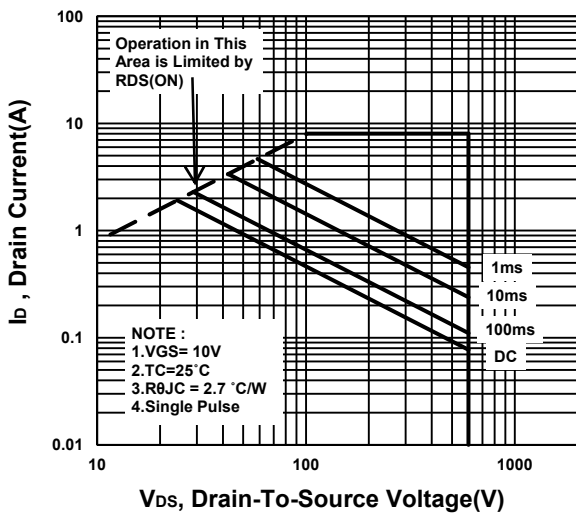
On-Resistance VS Temperature



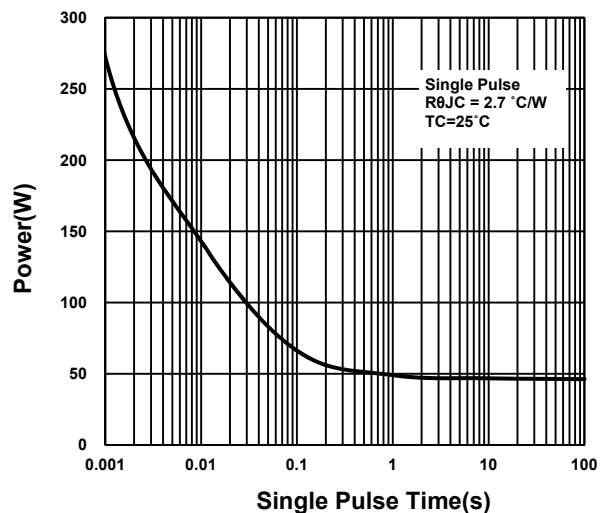
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

